

Config Data for S/N =

F13004HB

OS

3G.07.12

Boot ROM

03.06.00

Wafer Cassette Frame (TSK)	2-8-1
Hot Chuck Controller	Present
Wafer ID	BCR
Needle Inspection	PMI-1
Auto Needle Alignment	Yes
Auto Needle Height	Yes
GP-IB	Yes
GP-IB Command	TSK Standard
Off Site Marking	Yes
Drive Marker by Category	No
Cleaning Unit	Unit
Cleaning Unit dimensions	90 X 200cm
Chuck Type	Porous/Ambient
Multi Pass Probing	Yes
Automatic Card Changer	No
Group Index Option	Yes
Group Management Option	Yes
Remote Mode Setting	Invalidity
Network Boot Method	Hard Disk
Perform Network Function	Yes
Perform Logging Data Up	Yes
Printer	Internal
E2 Camera Low MAG	Coaxial+Oblique
Bump Height Measurement	Yes
Card Guide Drawer	Yes
High Rigidity Chuck	Yes
Alignment Camera Type	E5
Z-Axis Stroke	Long
Y Axis Origin	4mm Front
Prober Remote Terminal	New Type
X/Y Morie Scale Type	Special
Kind of CPU Board	Advme 7507
Large Storage Media	MO
RS232	1-3
Use Offsite Marking	Yes
BCR Type	Siemens Lk-Series
Wafer Sensing Method	Special
Dual Alignment Model	Between Probers
Parameter Mask Set Sys Level	Yes
Lot Set/Up Manage by Barcode	Yes
S2 Option	Yes
Image Processing Board type	C8200
Frame Handling	Yes
CSP Alignment Option	Yes
Frame Rotation Option	Yes
V4400 Series Card Change Pos	Standard

Power Supply Measurement	Measured
AC Supply	208 AC
5 VDC	5.0 VDC
24 VDC	24.1 VDC
12 VDC	11.9 VDC
24 VDC	24.1 VDC
Connectors	
CN1	CNTRL
CN4	GPIB
CN5	Ethernet
CN6	Ext.Prn
CN9	Ethernet 2